

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10563463			
<b>Filing Date:</b>	05-Jan-2006			
<b>Title of Invention:</b>	Cucurbituril derivative-bonded solid substrate and biochip using the same			
<b>First Named Inventor/Applicant Name:</b>	Kimoon Kim			
<b>Filer:</b>	Joseph A. Hynds/Jessica Fu			
<b>Attorney Docket Number:</b>	1751-393			
Filed as Small Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
Petition fee- 37 CFR 1.17(h) (Group III)	1464	1	130	130
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Statutory disclaimer	2814	1	70	70
<b>Total in USD (\$)</b>				<b>200</b>